

In the Specification:

On page 12 of the specification, please amend paragraph [0028] as follows:

Figs. 3A and , 3B and 3C are plan and cross-sectional views respectively illustrating lead frames having a dimple type lead lock in accordance with a third embodiment of the present invention;

On page 12 of the specification, please amend paragraph [0029] as follows:

Figure 3C 3D is a cross-sectional view partially illustrating a semiconductor package fabricated using a lead frame provided with at least one aperture, in place of the dimple, as the lead lock;